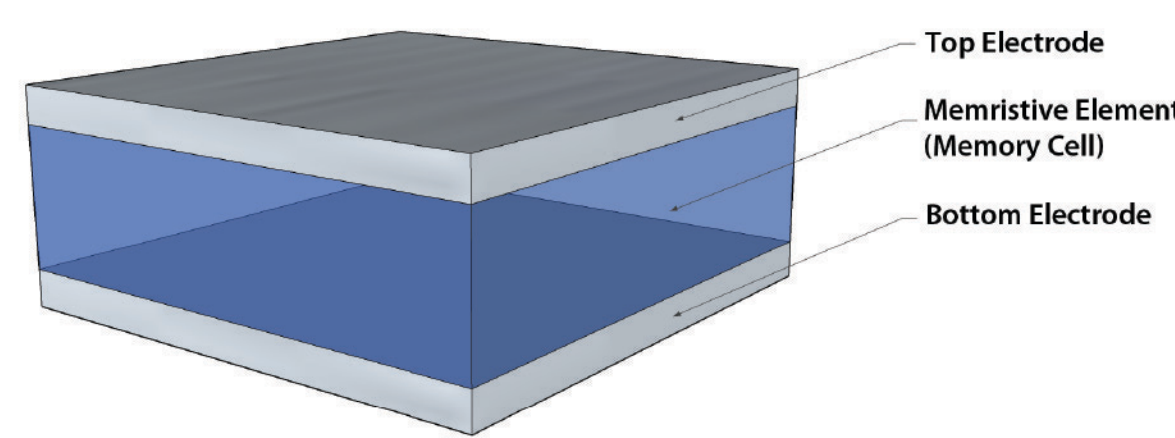
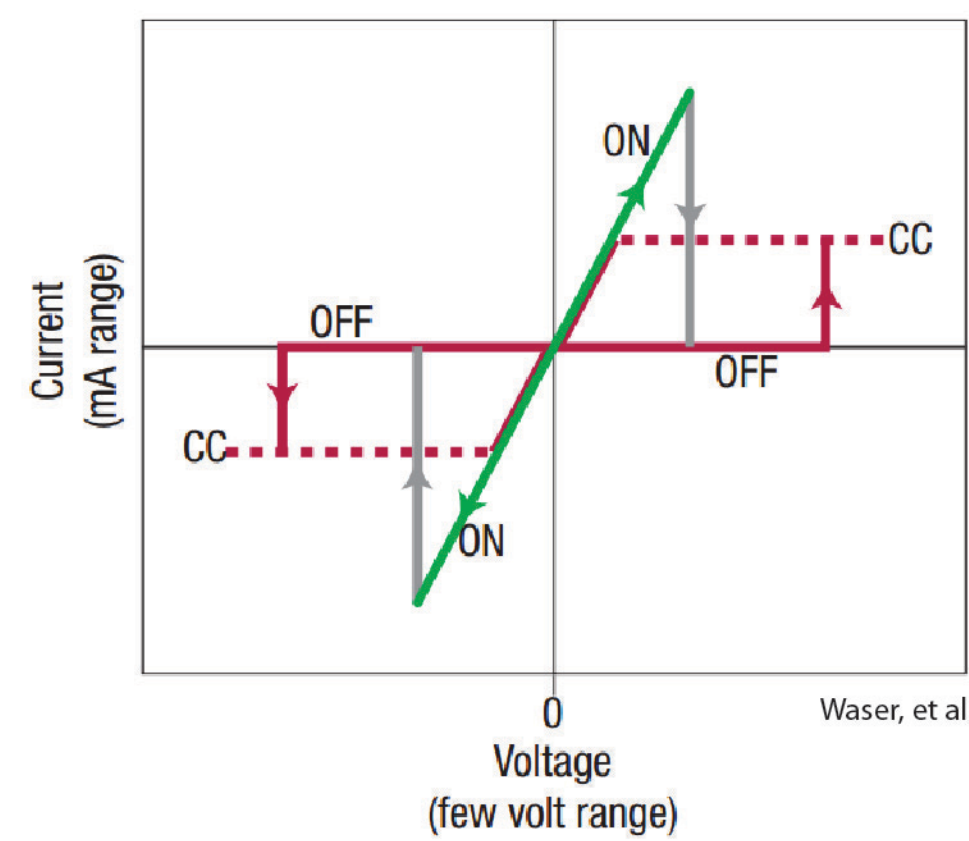


# Transition Metal Oxide Resistive Memory

Wilkie Olin-Ammentorp  
Advisor: Dr. Santosh Kurinec

## Introduction

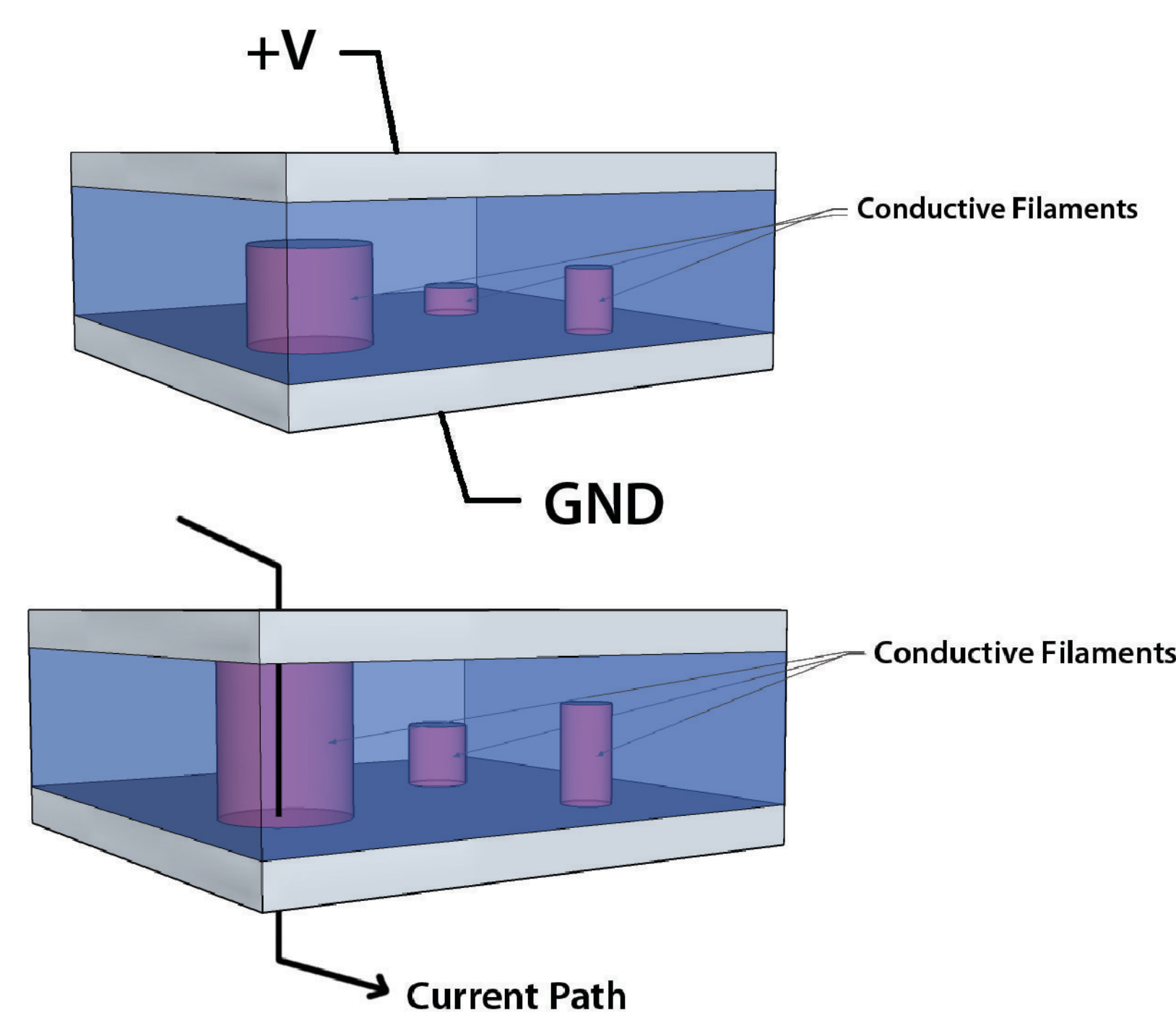
- NAND flash has reached fundamental scaling limits.
- To continue 2D scaling of memory, a new type of memory must be used.
- Resistive random access memory (RRAM) is a leading candidate to replace flash.
- In RRAM, a passive element stores information by changing resistance.
- Low current levels can be used to read the cell, and high currents or voltages can be used to program it.
- Devices which change their resistance state based on previous biasing conditions are called “memristive.”



- Transition metal oxides are a class of materials which can change resistance by undergoing a reversible soft breakdown.
- These materials include titanium dioxide, hafnium dioxide, and nickel oxide.
- A process was created to fabricate devices which could investigate this memristive behavior.

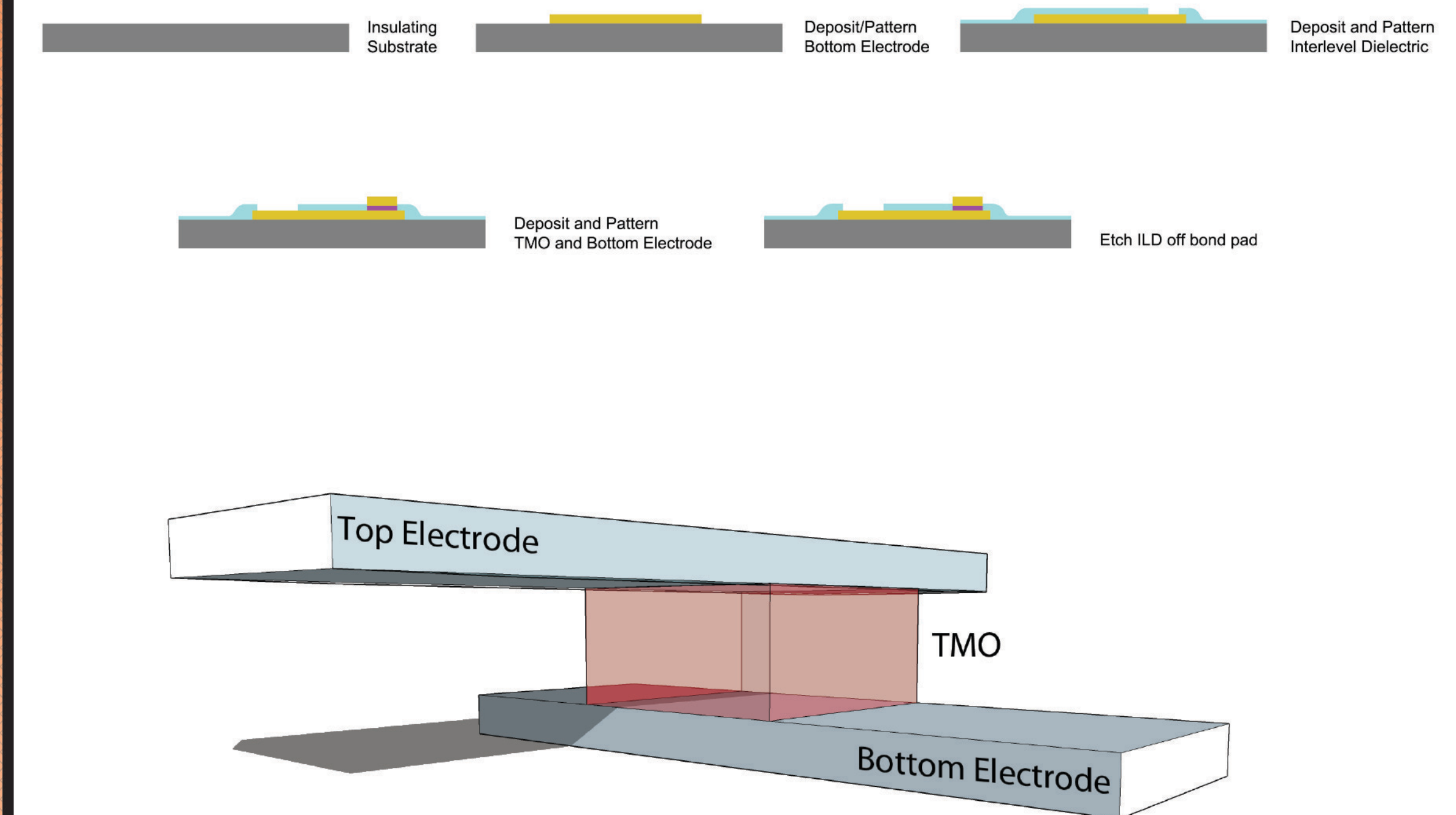
## Theory

- A great deal of research has focused on titanium dioxide, making it the best-characterized memristive film.
- Titanium dioxide can form many phases, some of which are conductive and some of which are insulating.
- Under-stoichiometric films with oxygen vacancies are conductive.
- Electrical biasing can drive a reaction to create oxygen vacancies.
- These vacancies can rearrange into filaments which conduct current through the material.
- High currents passed through the filaments causes them to heat, which causes the filament to react and/or dissipate.

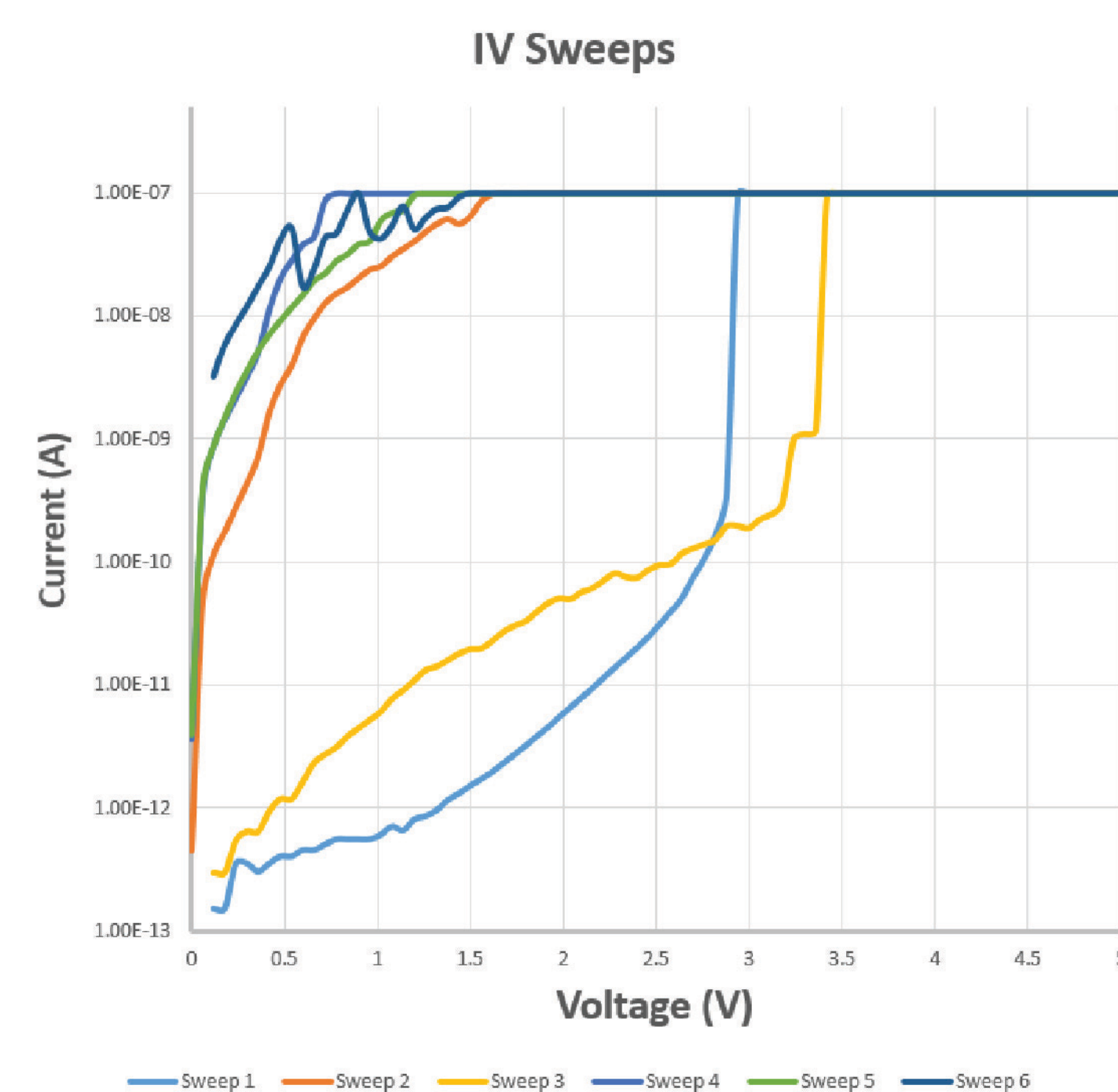


## Process

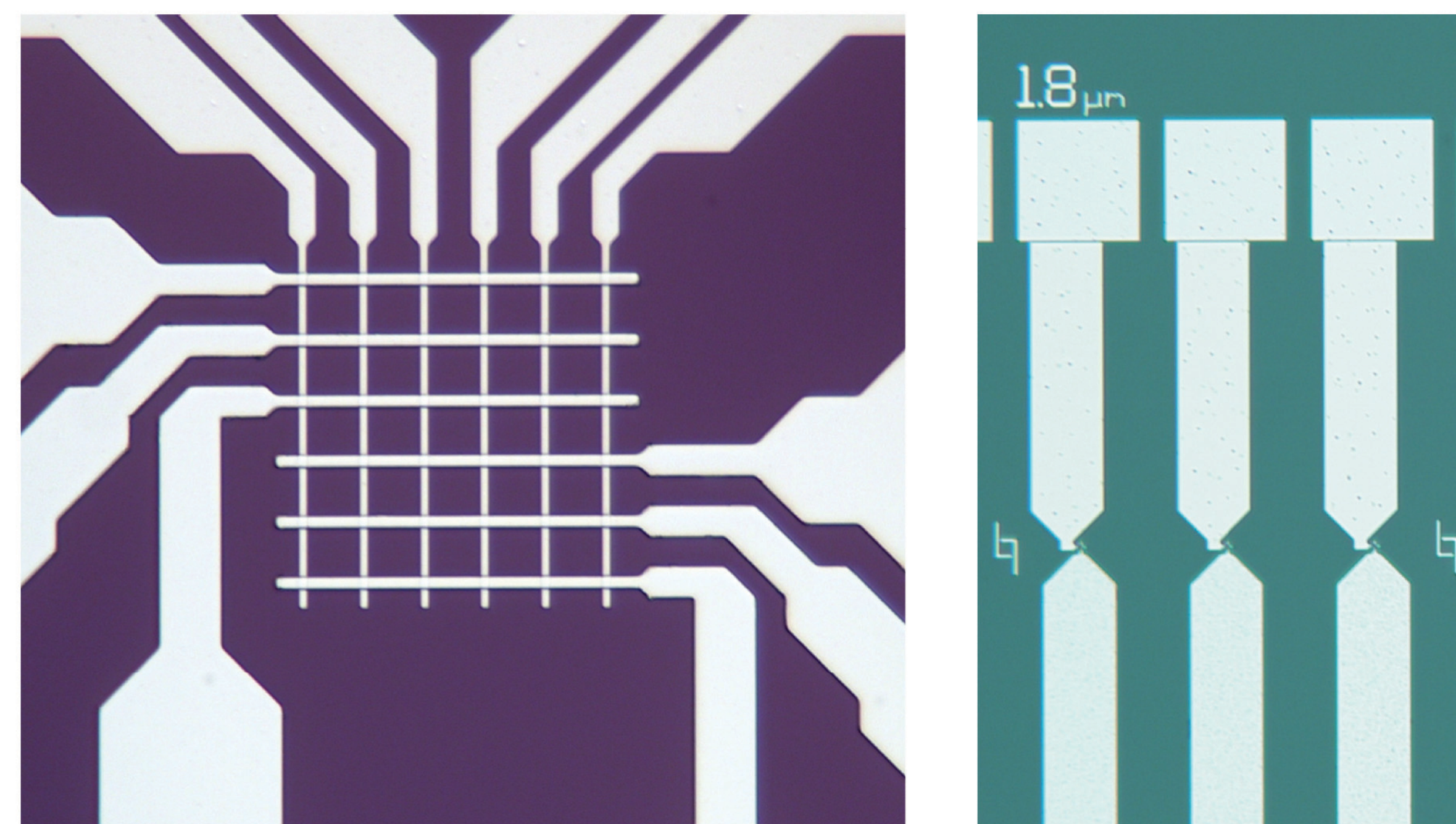
1. Prepare insulating substrate
2. Deposit and pattern bottom electrode
3. Deposit and pattern inter-layer dielectric
4. Deposit memristive transition metal oxide (TMO) film
5. Deposit and pattern top electrode
6. Etch interlevel dielectric over bond pad
7. Electrical test



## Results



- Devices were created using aluminum top and bottom electrodes and a under-stoichiometric titanium oxide film.
- Electrical testing confirmed that the structures could switch between a high and low resistance state.
- On average, the on/off ratio was  $10^4$  at 1 V.



## References & Acknowledgements

### Acknowledgements:

Dr. Santosh Kurinec  
Dr. Michael Jackson  
Dr. Karl Hirschman  
Dr. Casey Miller  
SMFL Staff: Patricia Meller, Sean O'Brien, John Nash, Bruce Tolleson, Rich Battaglia, Scott Blondell, Dave Yackoff, Tom Grimsley  
Karine Florent  
Matt Filmer  
Jim Carroll  
Eric Pethybridge

### References:

- [1] D. Acharyya, A. Hazra, and P. Bhattacharyya, "A journey towards reliability improvement of TiO<sub>2</sub> based Resistive Random Access Memory: A review," *Microelectronics Reliability*, 2013.
- [2] J. P. Strachan, J. J. Yang, L. A. Montoro, C. A. Ospina, A. J. Ramirez, A. L. Kilcoyne, et al., "Characterization of electroforming-free titanium dioxide memristors," *Beilstein J Nanotechnol*, vol. 4, pp. 467-73, 2013.
- [3] J. J. Yang, D. B. Strukov, and D. R. Stewart, "Memristive devices for computing," *Nat Nanotechnol*, vol. 8, pp. 13-24, Jan 2013.